

OBSERVATIONS OF SINGLE EVENT FAILURE IN POWER MOSFETS

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Abstract

This first compendium of single event test data for power MOSFETs provides failure thresholds from burnout or gate rupture for over 100 devices of eight manufacturers. Ordering the data has also provided some useful insights.

I. Introduction

Power transistor single event effects (SEE) test data obtained by The Aerospace Corporation, The Boeing Company, Jet Propulsion Laboratory, NWSC (Crane, IN), Rockwell International, and others have been organized into one compendium here. The intent is to present a nearly comprehensive set of MOSFET data through May, 1994. It is believed, however, that some other data may be available that has not been published or brought to our attention. Contributors who desire inclusion in this compendium should contact Don Nichols.

This data set includes both single event burnout (SEB) anti single event gate rupture or damage (SEGR or SEGD) of MOSFET power devices. There is no hard line of separation between power devices and lower power devices, nor is there a demonstrated immunity of the latter to SEE. There is some data (not shown) for SEB of npn bipolar devices but none (as yet) of burnout of pnp bipolar devices. The bipolar data is still very limited and much of it was taken by Titus et al (1) who have refrained from identifying manufacturers. Thus the category of bipolar power transistors is still very rudimentary.

The purpose of the present work is to:

- (1) provide design engineers with operating voltage limits (max V_{DS} for a specified V_{GS}) of tested devices.
- (2) identify unspecified process variables relevant to SEE response
- (3) identify those parameters characterizing SEE response
- (4) present trends that permit extrapolation from the existing data set,

II. Testing Approaches

There are several possible testing approaches that have been considered, but two are of fundamental importance. One approach attempts to measure the SEB/SEGR cross section vs V_{DS} of a device for a given test ion (or equivalently a given LET) for a fixed gate source voltage (V_{GS}) and temperature. This type of cross section should not be confused with the LET-dependent cross sections tabulated for soft errors in ICs. The transistor cross section equals zero at lower V_{DS} and rises very rapidly only at its threshold V_{DS} (almost like a step function); then tends to level off at somewhat higher V_{DS} . So far, no experiment has yet extended the data far beyond threshold. Then, to obtain SEE rates for a specified environment, one must perform the same experiment for several other ions to establish the LET threshold and cross sections for a few different ions (LETs) above threshold. This approach requires a large sample size and still does not provide an adequate basis for calculating the device upset rate. All of the preceding cross sections must also be repeated for angles of beam incidence greater than zero.

The second approach seeks simply to identify the threshold voltage $V_{DS(th)}$ for failure for a given ion (usually Ni/Au or Br/Kr), V_{GS} and temperature. The selected ion should represent a realistic worst case for the environment. The latter approach indicates a voltage operating limit to the designer who can apply a derating factor, but it also offers

“little chance, to estimate the failure probability if one operates above threshold.

The data tabulated here in one extended table presents threshold V_{DS} for several groups of ions at a few selected gate source voltages V_{GS} , following the second (recommended) approach.

A nearly standard technique* for measuring the threshold drain-source voltage V_{DS} consists of the following steps :

(1) Prior to any irradiation, measure the drain source current at rated BV for $V_{GS}=0$, or alternatively measure the actual breakdown V_{DS} for the same conditions. One should also measure the gate-source current at maximum rated gate voltage (usually 20 V) for $V_{DS}=0$. These measurements establish the normal operating currents.

(2) Choose a single gate voltage V_{GS} (start with the least susceptible zero voltage) and hold it constant for each subsequent irradiation step, for successively larger V_{DS} . At the end of each irradiation step of 105 ions/cm², change the bias conditions to those used in step (1) to determine the two currents I_{GSS} and I_{DSS} .

(3) Failure is either (1) SEGR as evidenced by a large permanent increase in gate current ranging between a fraction of a milliamp up to the circuit limit (say, 10 amps) or (2) SEB (burnout) evidenced by a short across source and drain as well as a gate short.

(4) Delayed Failures-- On several occasions JPL and other test organizations have seen delayed types of SEGR. On some occasions, the gate currents increased to -1 mA during irradiation and then increased again to the circuit limit during post-beam tests where, as always, V_{GS} was reset to 20V.

“Another type of SEGR failure occurs when the drain-source voltage is incremented for the next test,

111. Supporting Studies

Several collateral tests have been performed by now. Nichols et al (2), Fischer (3) and Tastet (4) have demonstrated that higher grazing angles of ion incidence have less effect on SEB and SEGR than normally incident irradiation. Hence the complications involved in calculating SEE rates by dealing with an effective LET vs incident ion angle are simplified. (In actuality, there is no known formal method for calculating rates under these conditions for a specified environment. Since the calculation is relatively easy when compared to those for incident ions on other microcircuits, it is expected that such a rate calculation method will be developed soon.)

*At present, no standard test approach has been described. The second approach outlined here is recommended when a large number of device types must be evaluated for a proposed system.

High temperature tests have been performed (2,S.6) showing that SEB is greatly reduced at higher temperatures due to phonon interference with the avalanche burnout mechanism. In contrast, high temperatures tend to promote SEGR to a varying degree.

Nichols and Waskiewicz have noted that most transistors that are supposed to differ only by die size (e.g. by having a different number of the same size transistor elements or cells) have similar breakdown voltages as expected. However, there are a few occasions when such devices yield widely different SEE results. Waskiewicz notes that the dielectric oxide breakdown voltage (an uncontrolled parameter) may be responsible for wafer-to-wafer anti device-to-device variability to SEE.

Oberg has demonstrated that the failure threshold voltages increase with device rated breakdown voltage as expected, but not at a proportionate rate. The threshold voltage as a percentage of breakdown voltage BV tends to decrease as BV increases.

IV. Organization and Scope of Data

This paper presents SEB and SEGR data for MOSFETS in Table 1 for all known data taken up to May, 1994. Eight manufacturers are represented, with especially extensive data for International Rectifier (INR) and Harris (HAR). Most data are for commercial parts; but Harris, Ixys and INR have developed devices which are resistant to total dose. These rad hard devices often turn out to be less susceptible to burnout as well, but some hardening techniques (such as oxide thinning) may cause the devices to be more susceptible to SEGR.

The data have been provided directly by testers or taken from published records of tests performed by many organizations. Most data is taken at ambient temperature; data taken at higher temperatures is noted in the "Remarks" column. One advantage of this type of data compilation is to point out and exclude inconsistent data. One example is the data set taken in 1987 that used low energy ions at the University of Washington tandem Van de Graaff. More recent tests at that facility, by Boeing, with the "Booster" accelerator, utilized higher energy ions and are therefore consistent with data taken at other accelerators. As can be seen, the remaining test results demonstrate a strong correlation between higher-LET incident ions and a lower acceptable drain-source voltage threshold. There is also a strong correlation between higher off gate-source voltage V_{GS} and lower V_{DS} thresholds.

The data are grouped in rows by device manufacturer with the smallest manufacturer data groups listed first. Within each manufacturing group, devices with the lowest breakdown voltage are listed first-- first n-channel and then p-channel. Devices that are very similar, or the same devices tested with different conditions (e.g. V_{GS}) are grouped in touching,

adjacent rows. The columns list manufacturers, device number(s), channel type, and test sample size. It is observed that samples are never large enough to provide valid statistics, nor a characterization of maverick behavior that is occasionally noted. Most data, however, are fairly repeatable. Subsequent columns list the rated breakdown voltage (BV) and gate-source voltage V_{GS} .

The next five columns group the ions. The first column is for low-LET ions having LETs less than that of the dominant Ni/Fe/Co/Cu group included in column two. This first group is useful in judging the adequacy of postulated theories (See for example, ref. 3). It is now often accepted that a characterization with a single ion of the second group may be all that is needed for project requirements. This view is supported by two facts: (1) those heavier ions having a higher LET have fluxes in outer space two or three orders of magnitude smaller than that of the Ni/Fe group, and (2) there is no need to account for enhanced effects from grazing-angle collisions having a high "effective" (angle-dependent) LET. The third group in the table includes Br and Kr (LET=37 MeV/mg/cm²), traditional high LET ions at the Brookhaven Van De Graaff (BNL) and U. C. Berkeley 88-inch cyclotron (88), respectively. The fourth group includes the highest LET ions easily available at the aforementioned facilities. The fifth column includes data from very high energy (10- 100 MeV/amu) facilities: the Berkeley Bevalac (now defunct) and GANIL (France). It is this last group of ions that present some inconsistencies with the lower energy LET characterizations, for reasons that have not yet been fully explained.

The remaining set of columns provide the failure mode, the test group, test date, ion facility and "Remarks." It is useful to know that INR uses 7000 and 8000 numbers to specify n-channel devices with 100 Krad and 1 Mrad total dose tolerance, respectively; 9000 numbers for p-channel devices with 100 Krad tolerance. The first INK mfr number (on the left) relates to the breakdown voltage; the second number is related to the die size-- the larger this number, the larger the die size and (usually) the larger number of individual cells. INK's letter "H" in the third place from the left of the prefix means that the devices are especially designed to be radiation resistant to total dose. It turns out that such devices are also very resistant to single event effects as well. The fourth letter of INR (which may be "1") and third letter of HAR devices is a package designation not expected to affect SEB/SEGR data. Harris denotes rad hard tolerance with a suffix after the device number; R= 100 Krad and H= 1 Mrad.

V. Future Directions

The large body of test data have led to generation of global models of SEB and SEGR. We know such models are not the whole story, for burnout data often show meltdown located at physical stress points, such as the edges of metal overlayers. We also note again that field-dependent irradiation models are not sufficient to explain the delayed failures caused by bias changes following irradiation.

The SEB model first mentioned by Waskiewicz (5) and Hohl (7, 8) has been polished and extended by Wrobel (9). This model seemed sufficient, but it has been challenged, at least in part, by Ku boyama (10) with an experimentally-based numerical analysis. Hence the picture of SEB cannot be considered a closed subject.

The model for SEGR has yet to be produced. The most recent attack on the problem was provided by the group at the University of Arizona (11,12) who attempt to match a numerical analysis of the semiconductor region to properties of the gate oxide. Their computerized approach, using a n-channel cylindrical (r,z) transistor cell, describes a normally incident ion track along the z-axis whose holes migrate to the oxide-semiconductor interface. The model assumes that the holes are not trapped at the interface, but that they pile up there before drifting transversely to the grounded body. The charge buildup at the interface is thus a sensitive function of the hole mobility and the RC time constant of the interracial storage capacitor. The model shows the expected variation in voltages and currents; it also demonstrates that the maximum time-dependent fields across the oxide are indeed sufficient to exceed the critical field characterizing oxide breakdown.

Some limitations of the above semiconductor model were amplified later (ref. 12) in order to explain the effect of grazing angle irradiation and higher temperatures on SEGR. Increased SEGR susceptibility at higher temperature is attributed to (1) increased concentration of holes at the interface due to decreased radial diffusion of deposited holes from the center of the ion's filament (track), and (2) a decrease of hole mobility.

The reduced chance of SEGR at higher angles, according to numerical simulations indicated by ref. (12), comes from the fact that the holes deposited in the oblique track are still driven vertically to the oxide-semiconductor interface. Because the hole charge is now spread over a wider area at the interface, a lower electric field is generated across the oxide.

Although neither description (of SEGR and SEB) can be considered complete, it seems clear that the greatest deficiency lies in our understanding of the oxide. Is there really a well-defined critical field and if so, what mechanism causes the abrupt collapse (short-circuiting) of the oxide? How long must the critical field last in the oxide before breakdown occurs? What controlled and uncontrolled oxide fabrication parameters affect oxide breakdown? Is there a first-stage incipient breakdown induced by heavy ions that is triggered by a later change, to higher applied bias? What role do mechanical stresses, impurities, structures and surfaces play? Can we find an oxide process resistant to SEGR and to totalizing dose?

Some possibilities for further numerical analysis still remain. Is a fully 3-dimensional code required to explain why a change in bias across the oxide is observed to be more influential than an equal change in bias across the drain-

source? Can we develop a 3-D code adequate to predict the performance of novel devices? Do possible interface traps play a significant role in SEGR models and their temperature dependence?

VI. Conclusion

This first compendium of SEB (SEB and SEGR) effects in power MOSFETs given here will be useful for designers of satellite and space systems. Some extrapolations may be warranted, and some cautionary observations are also provided. Testing with only one ion may be acceptable for some system requirements.

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4 Power MOSFET Data

Compilation of Single Event Data for Power MOSFETs--Threshold Voltages (Vds) for Normally Incident Ions for Burnout (SEB) and Gate Rupture (SEGR)

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z ions Fe,Ni,Co	LET=27 Br or Kr	LET-38	High Z ions High Energy Ions	Failure	Test Org	Date	Location	Remarks
The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L															
Ixys	20N60	n			5 0 0	5			280		SEB	B WP-01	11/93	88	Oberg Ambient . 25 deg C.
Ixys	20N60	n			500 5				300		SEB	B WP-01	11/93	88	Oberg Temp=100 deg C
Ixys	10 FA100	n		3	1000 5				450		SEB/SEGR	B WP-016/93		88	W Will DC SC9019 Ambient = 45 deg C
Ixys	10N100	n			1000 5				450		SEGR	B WP-01	6/93	88	W Will DC SC9019 Temp . 100 deg C
APT	APT40M42	n		3	400 12				200/225		SEB	HON WP-2	2/93	BNL	DC9302
	continued					+/-12 (dynamic)				200/225	SEB				
APT	1001R1AN	n		>2	1000 5				400		SEB/SEGR	B WP-01	4/93	88	DC 9126 W Will See next entry
APT	100 IR1AN	n		>2	1000 5				450		SEB/SEGR	B WP-01	4/93	88	DC 9126 W Will 100 deg C implies SEB
GEC	IRF150	2N6764	n	2	100 10		>95(Ne), 70(Ar)		70(Cu)		SEB	R/A	1990	88	
GEC	IRF250	2N6766	n	1	200 10		180(N), 170(Ne), <80(Ar)				SEB	R/A	1990	88	
UTR	IRFF320	2N6792	n		300 2?				<260(Cu)		SEB	R	1990	88	Compare to INR device
SIL		2N6660	n		60 10			27			SEB	A	6/88	88	Koga
SIL		2N6660	n	1	60 10		60(N), 50(Ne), 40(Ar)		22(Cu)		SEB	R/A	1990	88	
SIL		2N6660	n		60 5			40(N)			SEB	P	7/93	BNL	Revised fab last 2 yrs DC9230 Bob Ferndon
SIL	IRFF130	2N6796	n	2	100 10		100(N), 100(Ne), 70(Ar)		50(Cu)		SEB	R/A	1990	88	Compare to INR device
SIL	IRF150	2N6764	n	1	100 10		80(Ne), <50(Ar)		40(Cu)		SEB	R/A	1990	88	
SIL	IRF250	2N6766	n	2	200 10		160(N), 60(Ar)				SEB	R/A	1990	88	
SIL	IRFF230	2N6798	n		200 12			180"			SEGR	9 WP-01	10/93	UW	Oberg 100 deg C Worst case for SEGR
SIL	IRF350	2N6768	n		400 10				<120(Cu)		SEB	R	1990	88	
SIL	4 3 0 family	2N6802	n		500 5				300		SEB	B WPO1	4/93	88	Ambient=45 deg C
	(continued)					12			300		SEB/SEGR	B WP-01	10/93	UW	Temp=100 deg C

Manufacturers APT= Advanced Power Technology, GEC=Gen Electric, HAR= Harris, INR=Int'l Rectifier, Ixys=Ixys Corp, RCA, PCA, SII=Siliconix, UTR=Unitrode

Testers A= Aerospace (R Koga & W Crain), B= Boeing (D Oberg, J F Went & W Will), C= Crane NWSC (J Titus), HON= Honeywell (J Pollock, MDSSC, Houston, 713-283-1934), J= JPL (D Nichols, 818-354-5787)

JH= John Hopkins APL (J Kinnison), R= Rockwell (A Waskiewicz), S= Sandia (T Fischer), MMAS= Martin Marietta Aerospace (James Coleman, Valley Forge, PA), ESA (Len Adams)

Facilities 88= 88-in cyclotron (Berkeley), Bev= Berkeley Bevatron, BNL= Brookhaven Nat'l Lab Van de Graaff, GANIL= French National High Energy cyclotron, UW= U. of Wash., Van de G (low & medium energy modes)

4-Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns Hitthrough:

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z ions Fe,Ni,Co	LET=27 Br or Kr	LET=38 High Z ions	High Energy Ions	Failure	Test Org	Date	Location	Remarks
RCA	1 9 N 1 0		n		100	?					SEB	R	1990		Cf 252 data exists
RCA	IRF150	'2 N6764	n		100	10	100(N),100(Ne),50(Ar),	<50(Cu)			SEB	R	1990	88	
RCA	12P10		p	1	100	10	Hard(Cu)				N/A	R/A	1990	88	DC8445
RCA	IRF9130	'2 N6798	p	1	100	10	Hard (Cu)				N/A	PIA	1990	88	
RCA	30N15		n		250	?					SEB	R	1990		Cf 252 data exists
RCA	RFM12N18		n		180	0	100	90	65		SEB	A	5/88	88	Koga
QCA	IRF230	2N6758	n		200	10		105			SEB	A	6/88	88	Koga
RCA	IRF230	2N6758	n		200	27		<100(Cu)			SEB	Q	1990	88	
RCA	IRFF230	2N6798	n		200	2?		<90(Cu)			SEB	R	1990	88	
RCA	IRF250	2N6766	n	1	200	10	180(N),120(Ar),	80(Cu)			SEB	R/A	1990	88	
RCA	25N20		n	1	200	10	"200(N), 200(Ne), 180(Ar),	<70(Cu)			SEB	R/A	1990	88	
INR	IRFM054		n		60	5		No failure at 60"			N/A	B WP-01	4/93	88in	DC 9212 W Will
INR	IRHM7054		n		60	0	60(Ni)				N/A	R WP 04	7/93	BNL	DC9242 Bob Ferndon 7/1 3/93
	continued				5		60(Ni)				N/A	R WP-04	7/93-	BNL	DC9242 Bob Ferndon 7/1 3/93
INR	IRF110	2N6782	n		100	0		70/80(Ni)	50/70(Br)		SEB	ESA	11/94	BNL	9039B, Harwell Rept AEA RS 1348
INR	IRFF110	2N6782	n	1	100	10	100(N),100(Ne),90(Ar)	60(Cu)			SEB	R/A	1990	88	
INR	IRF120	2N6788	n		100	0	Hard(Ni)	80/90(Br)			SEB	ESA	11/94	BNL	9228G, Harwell Rept AEA RS 1348
INR	IRF120		n		100	2?	95(Ar)	<55(Cu)			SEB	R	R 1990	88	
INR	IRF120	2N6788	n		100	5	90				SEB	B	12/92	UW	Oberg 23 deg C Note failure mode vs temp
	continued				5		80				SEGR	B	12/92	UN	Oberg 80 deg c
INR	IRFF120	2N6788	n		100	2?		<60(Cu)			SEB	R	1990	88	
INR	IRH130		n		100	0	Hard @ 100(Br)	50160(!)			?	C	unknown	BNL	
	continued				10		Hard @ 100(Br)				N/A	C	unknown	BNL	
INR	IRHF130		n		100	0	Hard @ 100(Br)				N/A	J	1991	BNL	
	continued				7.5		<100(Br)				SEGR	J	1991	BNL	
	continued				15		<100(Br)				SEGR	J	1991	BNL	

4. Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z ions Fe, Ni, Co	LET.27 Br or Kr	LET=38 High Z ions	High Energy Ions	Failure	Test Org	Date	Location	Remarks	
INR	IRF130	2N6756	n	3	100	10	100(N),100(Ne),90(Ar)	60(Cu)				SEB	R/A	7/90	88	
INR	IRF130	2N6796	n		100	0	70/80(Ni)	60/70(Br)				SEB	ESA	1/94	BNL	8915A, Harwell Rept AEA RS 1348
INR	IRF130	2N6796	n		100	0		85				SEB	A	6/87	88	Koga
INR	IRF130	2N6796	n		100	5	Hard					N/A	B WP-01	3/93	88	Oberg DC9236
INR	IRFF130	2N6796	n	5	100	10	100(N),100(Ne),90(Ar)	60(Cu)				SEB	R/A	1990	88	Compare to SIL part
INR	IRFF130	2N6796	n		100	0		82(Br)				SEB	s	1990	BNL	220 MeV Br has range=28 microns
	continued				100	10		105(Br)	58(Au)			SEGR	S		BNL	330 MeV Au has range=31 microns
INR	IRF140		n		100	0	Hard(Ni)	70/80(Br)				SEB	ESA	1/94	BNL	9203E, Harwell Rept AEA RS-1348
INR	IRF150	2N6764	n		100	0	90/100(Ni)	70/80(Br)				SEB	ESA	1/94	BNL	9228G, Harwell Rept AEA RS 1348
INR	IRF150	2N6764	n	3	100	10	100(Ne),70(Ar)	50(Cu)		40/60(12 GeV La Bev)		SEB	R/A & J	1990	88	JPL Bevalac ion LET=30 6/88
INR	IRF150	2N6764	n		100	0	105	75	75			SEB	A	5/92	88	Koga
INR	IRF150	2N6764	n	3 each	100	off	100(1208 MeV Cl)	70(Ni)	55/Br	55(I)	50(1 to 4 GeV Xe GANIL)	SEB	ONES	11/90	BNL	3 GANIL ions Taster, RADECS91
INR	IRF150	2N6764	n		100	0	100(208 MeV Cl)	>80(Fe)			80/100(>1 GeV Fe) Bev	SEB	J	6/88	BNL	Two Fe at Bevalac, each ! ET-6
INR	IRH150		n		100	0	100(Fe)	100(Cu)	100(Kr)		60/100(12 GeV) La Bev	SEB	J & R	1990	88	JPL at Bevalac June 1988
	continued		n		100	10		100(Cu)	90/100(Kr)			?	R	1990	88	Waskiewicz & Groninger, DNA Rept 2/90
INR	IRHF7110		n		100	2	Hard at 100(Ni)	Hard at 100(Br)				N/A	R	7/92	BNL	90 deg C
	continued				100	15	Hard at 100(Ni)	70(Br)				SEGR	R	7/92	EVL	90 deg c
INR	IRHF7130		n		100	2	Hard at 100(Ni)	Fail at 100(Br)				SEGR	R	7/92	BNL	90 deg c
	continued				100	15	Hard at 100(Ni)	60(Br)				SEGR	R	7/92	BNL	90 deg C
INR	IRHM7130		n		100	5	80					SEGR	9 WPO1	1/93*	UW	100 deg C DC 9112
INR	IRH7150		n	6	100	0		Br Only	one of 6 fails, with 60/70 VDS			SEB	J	9/92	BNL	A maverick
	continued			4	100	15		60/80(Br)				SEGR	J	9/92	BNL	Data @ 100 deg C exists for Vgs=15 only
INR	IRH7150		n	2/3 ea	100	off	100(Ni)			>80(Xe)	GA NIL	N/A	ONES	11/90	GANIL	3 GANIL ions Taster, RADECS91
INR	IRH7150		n		100	0	Hard @ 100(Br)		.1 O(II)			?	c	unknown	BNL	
INR	IRH7150		n		100	0	Hard @ 100(Kr)		>100(Xe)			N/A	A	5/92	88	Koga reports no SEB up to 150 V
INR	IRFG6110		n&p	CMOS	100	2	85(Fe)--p ch only					SEB on MM AS WP2	5/93*	BNL	DC 9118 No SEGR No SEB p ch devices	
INR	9120 family	2N6845	p		100	2	Hard @ 100(Ni)	Hard @ 100(Br)				N/A	R WP 4	8/92	BNL	DC9218 90 deg C
	continued				100	15	Hard @ 100(Ni)	60(Br)				SEGR	R WP 4	8/92	BNL	DC9218 90 deg C
INR	IRF9122		p	1	100	10	Hard(Cu)					N/A	R/A	1990	88	DC8511

4-Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions	Fe, Ni, Co	LET.27 Br or Kr	LET=38 High Z ions	High Energy Ions	Failure	Test Org	Date	Location	Remarks
INR	9130	family2N6804	p		100	2						N/A	R WP-4	8/92	BNL	DC9141 90 deg c
	continued					15						SEGR	R WP-4	8/92	BNL	DC9141 90 (leg C)
INR	IRHF9130		o	5	100	0						N/A	R	4/93	BNL	90 deg C First INR hardened p channel
	continued			5		5						N/A	R	4/93	BNL	90 deg C
INR	IRFF9130	2N6849	d	2	100	10						N/A	R/A	1990	88	DC8533, 8547
INR	IRFF9130	2N6849	p		100	0						N/A	s	1987	BNL	
	continued					0 to 35						SEGR	s	1987	BNL	
	continued					36						SEGR	s	1987	BNL	
INR	IRF9130		p	2	100	10						N/A	R/A	1990	88	DC8406, 8545
INR	continued					10						N/A	s	unknown	BNL	
INR	IRF9140		p	3&2	100	0			60/70(Fe)			SEGR		91/92	BNL/88in	Anomalous comparison Vds of Br and Ar
	continued			3&3		15			Hard(Ar)			SEGR		91/92	BNL/88in	
INR	IRF9150		p	5	100	0						N/A	R	12/92	BNL	90 deg C
				5		5						N/A	R	12/92	BNL	90 deg c
INR	IRH9150		o		100	0	s	5				N/A	Q	8/93	BNL	DC A9330 Bob Ferndon
INR	IRF210	2N6784	n		200	0			140/150(Ni)			SEB	ESA	1/94	BNL	9228G, Harwell Rept AEA RS1348
INR	IRF210	2N6784	n		200	off			<130(Cu)			SEB	R	1990	88	
INR	IRF220		n		200	5			145(Co)			SEB	B WP-01	6/93	88in	Ambient=45 deg C DC 9218G W Will
	continued					5			150(Co)			SEB	B WP-01	6/93	88in	100 deg C W Will
INR	IRFF220	2N6790	n		200	5			145(Ni)			SEB	R WP-04	7/93	BNL	DC 9040 Bob Ferndon
INR	IRF230	2N6798	n		200	0			160/170(Ni)			SEB	ESA	1/94	BNL	9228G, Harwell Rept AEA RS1348
INR	IRFF230	2N6798	n		200	2?			<120(Cu)			SEB	R	1990	88	
INR	IRFF230	2N6798	n		200	0 & 5			135(Ni)			SEB	R	7/93	BNL	DC 9146 Bob Ferndon
INR	IRFF230	2N6798	n		200	0						SEB(Br)/SEGR (Au)	S	unknown	BNL	
INR	IRFF230	2N6798	n		200	0			140			SEB	B WP-01	10/93	LW	DC 9217 Oberg 22 deg C
INR	IRFF230	2N6798	"		200	5			120			SE B/SEGR	B WP-01	10/93	LW	Oberg 90 deg c
INR	IRF240				200	0			140/150(Ni)			SEB	ESA	1/94	BNL	9228G, Harwell Rept AEA RS1348

4-Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions Fe, Ni, Co	LET.27 Br or Kr	LET.38 High Z Ions High Energy Ions	Failure	Test Org	Date	Location	Remarks		
INR	IRF250	2N6766	'n		"200	o		"120/ 140(Ni)	<120(Br)		SEB	ESA	'1/94	BNL	9228G, Harwell Rept AEA- RS-1348	
INR	IRF250	2N6766	n		200	0		150	135		SEB	A	'9/89	88	Koga	
INR	IRF250	2N6766	'n		'200	0?		140(Fe), 120(Cu) 100(Kr)			SEB	A & B	1988	88/Bev	Oberg & Kolasinski	
	continued			2		10		190(Ni), 200(Ne), 120(Ar), 90(Cu), 100(Ni), 85(Br) - 150(Cl-252)			SEB	R/A	1990/1	992	88/BNL	Waskiewicz
	continued			3	each	off		200(Cl-2) 135(Ni) 112(Br) '107(I) 100(Xe)			GANIL SEB	ONES	11/90	BNL	3 GANIL ions Tastet, RAE) ECS91	
INR	IRF250	'2 N7225	n		'200	5		150			SEB	9 WP-01	11/93	88	Temp= 25 deg C	
						5		160			SEB	B WP-01	11/93	88	Temp. 100 deg C	
INR	IRH7230		n	5	200	'o		Hard at 200 V(Ni)			N/A	R	12/92	BNL	DC 9042 90 deg C	
	copntinued			'5		5		Hard at 200 V(Ni)			N/A	R	1 2/92	BNL	DC 9042 90 deg C	
INR	IRHF7230	2N7262	n		200	2		Hard at 200V(Ni) 160(Br)			SEGR	R	7/92	BNL	IR 7xxx =Rad tolerant 90 deg C	
	continued			'5		'15		1 fad at 200 V(Ni) 90(Br)			SEGR	R	7/92	BNL	1 of 5 fail-- Ni 90 deg C	
INR	IRH7250		n	4	200	0			Hard @ 200(Br)		N/A	J	91/92	BNL		
	continued			3, 2, 4		15		180/200(Ar) 160/200(Fe) 120/140(B,)			SEGR	J	91/92	BNL	Data @100 deg C exists for Br Vgs=15 only	
	continued			2		"20		80(Br)			SEGR	J	91/92	BNL		
INR	IRH7250		n	2/3	ea	'200	off	200(Ni)		200(Xe)	GANIL	ONES	1 1/90	GANIL	3 GANIL ions Tastet, RADECS91	
INR	IRH7250		n		200	0		180(Ni)			SEGR	R	8/93	BNL	T=90 deg C. DC A9316 Ferndon 818-586-2607	
	continued				'5			120(Ni)			SEGR	R	8/93	BNL	T=90 deg C DC A9316 Ferndon 818.5862607 !	
INR	IRHM7250		n		200	'5		No failure @ zoo			N/A	B WP-01	1/94	88in	Oberg 100 deg C	
					'12			170			SEGR	B WP-01	1 /94	88in	Oberg 100 deg C	
INR	IRHM8250		n	4	"200	'o		140			SEGR	B WP-01	1/93*	UW	Oberg 100 deg C	
	continued				200	5		110			SEGR	B WP-01	1/93	Lw	Oberg 100 deg C	
INR	9 2 3 0 family	2N6851	p		200	5		160			?	B WP 01	'1993	UW?	SSF Table	
INR	9 2 3 0 family	2N6851	p		200	'5		fails at 200			SEGR	B WP-01	'11/93	88	Oberg Temp .80 deg C	
INR	IRFF9230		p		200	10			Hard @ 200(Br)		N/A	s	unknown	BNL		
INR	IRFF9230	2N6851	p		200	0			Hard @ 200(Br)		N/A	s	1987	BNL		
	continued					o to 35				Pass at 0 (Au)	SEGR	s	1987	BNL		
	continued					36				Fail at 0 (Au)	SEGR	S	1987	BNL		
INR	IRFF9230	2N6851	p		200	0 & 5		Hard(Ni)			None	R	'8/16/93	BNL	DC A9330 Redesigned Bob Ferndon	
INR	IRFF9230	2N6851	p		200	10		Hard(Cu)			None	R/A	1990	88	DC8607	
INR	IRF9240	2N7237	P	2&2	200	0		80/100(Fe) 80/100(Br)			SEGR	J	91/92	BNL	Same Vds range for Br at 125 deg C	
	continued			3,1,3		15		Hard(Ar) 100/120(Fe) 80/100(Kr)			SEGR	J	91/92	BNL & 88in	Fe datum @ Vgs= 0(above) is anomalous	
	IRF9240				5			<200(Co)			SEGR	B WP 01	8/93	?	W Will 100 deg C Temp dependence is SEGR	
	continued				5			No failure			N/A	B WP 01	11/93	88in	Oberg Ambient Compare preceding	

4. Power MOSFET W

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L														
Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions	Fe, Ni, Co LET=27 Br or Kr LET=38	High Z Ions	High Energy Ions	Failure Test Org	Date	Location	Remarks
INR	IRH254		n		250	27				Hard(Cu) >225 (Kr)	7	R	1990	88
	continued		n		250	10	Hard(Ar)			Hard(Cu) 225/250 (Kr)	?	R	1,9%	88
INR	?	2N6780	n		400	0				200/240(Br)	SEB	ESA	*1/94	BNL Commercial, Harwell Rept AEA RS 1348
INR	IRF310	2N6786	n		400	0		260/270(Ni)		250/260(Br)	SEB	ESA	*1/94	BNL 9228G, Harwell Rept AEA RS-1348
INR	IRFF320	2N6792	n		400	2?				<260(Cu)	SEB	R	1990	88 Compare UTR device
INR	IRF330	2N6800	n		400	0		240/260(Ni)		200/240(90)	SEB	ESA	-1/94	BNL 9228G, Harwell Rept AEA RS-1348
INR	IRFF330	2N6800	n		400	2		<235 (Cu)		235(Br)	SEB	P	7/92	BNL 90 deg C
	continued					15				235(Br)	SEB	R	7/92	BNL 90 deg C
INR	IRFF330	2N6800	n		400	5		240(LET=28)			SEB	B WPO1	12/92	UW 100 deg C DC E9115
INR	IRF340		n		400	0		250/260(Ni)		240/280(Br)	SEB	ESA	*1/94	BNL 9228G, Harwell Rept AEA RS-1348
INR	IRF340		n		400	2?		245			SEB	MM-AS wP2	*8/93	BNL? DC 8924,9031,9110 Dr T Rao Satish
INR	IRF350	2N6768	n		400	?				130 (LET=32)	SEB	CNES	1 992	GANIL Dufour et al'92 IEEE Workshop
INR	IRF350	2N6768	n		400	5		260			SEB	B WP-01	*6/93	88 in Oberg Vth=280 at 100 deg C
INR	IRF350	2N6768	n		400	0		260/280(Ni)		200/240(Br)	SEB	ESA	-1/94	BNL 9228G, Harwell Rept AEA RS 1348
INR	IRH7360		n		400	7		Hard @ 400			N/A	INR	1/93	BNL IR 7xxx Rad toleranc
INR	IRHM7360		n	6(Ni)	400	0 to 2		175/200(Ni)		220(Br)	SEGR	R	7/92&4/93	BNL 90 deg C
	continued			5(Ni)		5		175/200(Ni)			SEGR	R	12/92&4/93	BNL 90 deg C
	continued			5(Ni)		7		175/200(Ni)			SEGR	R	4/93	BNL 90 deg c
	continued					15		No data		125(Br)	SEGR	R	7/92	BNL 90 deg C
INR	IRF360		n	4	400	?		225/250			SEGR	HON WP 2	2/93	BNL DC9238G
	continued					12				<250	SEB			
	continued							+/-12 (dynamic)		>300	SEB			
	continued									.250	SEB			
INR	IRF360		n	5&4	400	0		220/230(Ni)		225/250(Br)	SEB	R	9 & 12/92	BNL DC9143 B, 90 deg C N, @ room T
	continued			5&1		5		220/250(Ni)		225/250(Br)	SEB			
INR	IR 420	2N6794	n		500	5		300 at high T			SEB	B WP-01	11/93	88 Oberg Datum at 100 deg C only

4: Power MOSFET Data

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions	Fe, Ni, Co	LET=27 Br or Kr	LET=38 High Z Ions	High Energy Ions	Failure Test Org	Date	Location	Remarks		
INR	IRF430	2N6802	n		500	0			300/350(Ni)		320(Br)	SEB	ESA	.1 /94	BNL	9228G, Harwell Rept AEA-RS-1348	
INR	IRF430	2N6762	n		500	7					<310(Cu)	SEB	R	1990	88		
INR	IRFF430	'2 N6802	n		500	?					500(Au)	SEB	JH		BNL	Au has inadequate range =27mic	
INR	IRFF430	'2 N6802	n		500	?					275(LET=100)	SEB	JH		BNL	J Kinnison	
INR	IRFF430	'2 N6802	n		500	5			325			SEB	B WP-01	"4/93	88in	Oberg ambient .45 deg C>	
	(continued)				"	1 2			325			SEB	B WP-01	"10/93	UW	Oberg Temp =100 deg C	
INR	IRF440		n		500	0			300/350(Ni)		250/300(Br)	SEB	ESA	"1/94	BNL	9228G, Harwell Rept AEA-RS-1348	
INR	IRF440		n		500	5			300			SEB	B WP-01	6/93	88	Oberg ambient .45 deg C	
INR	IRF440		n		500	12			325			SEB	B WP-01	6/93	88	Oberg Temp =100 deg C	
INR		2N6820??	n		?	5			"350			SEGR	B WP-01	6/93	UW?	W Will DC 9225	
INR	IRFM450	2N7227	n		500	0			370(LET=15)350(LET=30)		320(LET=40)	SEB	A	"9/93	88	Koga has cross sections for each LE	
INR	IRFM450	2N7227	n		500	?			350(Cl)	300(Ni)	275(Br)	250(1)	SEB	CNES	1 /90	BNL	
INR	IRF450	2N6770	n		500	0				300/350(Ni)	300 (Br)		SEB	ESA	.1 /94	BNL	9228G, Harwell Rept AEA-RS1348
INR	IRF450	2N6770	n		5 & 1	500	0		290/300(Ni)		275/300(Br)	SEB	R	9 & 12/92	BNL	Br @ 90 deg C , Ni @ room T	
	continued				5 & 3	5			290/300(Ni)		275/300(Br)	SEB	R	9 & 12/92	BNL	Br @ 90 deg C , Ni @ room T	
INR	IRF450	2N6770	n		500	?						250(LET=23)	SEB	CNES	1992	GANIL	Dufour et al 92IEEE Workshop
INR	IRH450		n		2/4 ea	"500 off			350(Br)		325(1)	250(Xe)-GANIL	SEB	CNES	11/90	BNL	3 GANIL Ions Test TRADECS91
INR	IRH7450		n		500	?					310 (Br)	SEB	CNES	1990	?		
INR	IRH7450	2N6770	n		5 & 5	500	0 to 2		300/325(Ni)		250/275(Br)	<120(1)	SEGR	R & C(only)	7,9,12/92	BNL	R 90 deg C Epi=40-50 mic for high V parts
	continued				5 & 4	5			275/300(Ni)		225/250(Br)		SEGR	R	9 & 12/92	BNL	90 deg C
	continued					15			"No data		155(Br)		SEGR	R	7/92	BNL	90 deg C
INR	IRHM7450		n		500	5			300				SEGR	B WP-01	"1/93	UW	Oberg Temp= 100 deg C
INR	IRGAC50U	IGBT	n		2(Ni)	600	0		340/350(Ni)			SEB	R	12/92	BNL	room T	
	continued	IGBT			2(Ni)	600	5		340/350(Ni)			SEB	R	12/92	BNL	room T	
INR	IRGAC50U	IGBT	n		600	5			380(Co)			SEB	B WP-01	6/93	88	DC 9300 W Will Temp .25 deg C	
INR	IRFAG30		n		1000	5			400			SEGR/SEB	B WP-01	6/93	88	DC 9227, W Will Temp .45 deg C	
INR	IRFAG30		n		1000	5			450			SEGR/SEB	B WP-01	6/93	88	DC 9227 W Will Temp . 100 deg C	

4. Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L

Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions Fe, Ni, Co	LET=27 Br or Kr	LET=38 High Z ions	High Energy Ions	Failure Test Org	Date	Location	Remarks
HAR	IRF130	2N6796	n		100	5			40(Co)		SEB	BWP-01	4/93	88in M9226 Oberg Same result at 45 & 100 deg C
HAR	FRM130	2N7271	n		100	5			100		None	Harris	-? 993"	BNL? SSF Table
HAR	130 family	2N6756	n		100	5			41		?	Harris	1993 -	BNL? SSF Table
HAR	FRM140D1	2N7283	n	2	100	0			70/80 (Br)		SEGR	J	91/92	BNL Data @ 100 deg C exists for Vgs=0 & 15
	continued			3"		15			20/40 (Kr)		SEGR	J	91/92	88-in *HAR says these are not latest technology
HAR	FRM140	2N7283	n		100	5			98		?	Harris	*1993"	BNL? SSF Table
HAR	FRK150R	2N7291	n	5	100	0			80/100 (Ni)		SEGR	RWP-4	12/92	BNL 90 deg C
	continued			4		5			80/100 (Ni)		SEGR	RWP-4	12/92	BNL 90 deg c
HAR	FRK150	2N7291	n		100	5			97		?	Harris	*1993-	BNL? SSF Table
HAR	FRK1600	2N7299	n	2	100	0			70/80 (Br)		SEGR	J	91/92	BNL
HAR	FRK160	2N7299	n		100	5			No failure at 100		N/A	Harris	*1993"	BNL? SSF Table
HAR	9110 family	RFL1P10	D		100	</=10			Hard @ 100		N/A	R	*1992	BNL
														for device coded data
HAR	9130 family	2N6849	P		100	5			No failure at 100		N/A	BWP 01	-3/93	88in Oberg Rm Temp
HAR	FRM9140R		P	4	100	0			60/70 (Br)		SEGR	J	91/92	BNL
	continued			3&3		15			90/100 (Ar)		SEGR	J	91/91	BNL 1 of 3 SEGR for A,
HAR	FRK9150R	2N7322	P	5 & 5	100	0			Hard @ 100 (Ni) 60/70 (Br)		SEGR	RWP-4	12/92	BNL DC928x 90 deg C >
	continued			5 & 5		5			Hard @ 100 (Ni) 50/60 (Br)		SEGR			BNL 90 deg c
HAR	IRF9150		P		100	-o			Hard @ 100V		N/A	R	1992	BNL DC9010
	continued					10			Fail @ 100		SEGR			
HAR	FRK9160		P	3	100	0			60/70 (Br)		SEGR	J	91/92	BNL
HAR	FRK9160R	2N7328	P	5	100	0			80/90 (Ni)		SEGR	R	12/92	BNL 90 deg C Compare FRK9150R
	continued			3		5			70/80 (Ni)		SEGR	R	12/92	BNL 90 deg C Compare FRK9150R
HAR	FRM230R	2N7274	n	2	200	0			160/180 (Ni)		SEGR	R	12/92	BNL 90 deg C Compare FRK250R
	continued			2		5			160/180 (Ni)		SEGR	R	12/92	BNL 90 deg C Compare FRK250R
HAR	FRM230	2N7274	n		200	5			166		?	Harris	*1993"	BNL? SSF Table
HAR	FRK230R		n		200	0			140 (Ni)			RWP-04		BNL Temp - ?
	continued					5			120 (Ni)			RWP-04		BNL Temp - ?

4 Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L														
Mfr	Mfr Number	Generic No	Channel	Sample	BVds	Vgs(off)	Low Z Ions	Fe, Ni, Co, LET=27 Br or Kr LET=38	High Z Ions	High Energy Ions	Failure Test Org	Date	Location	Remarks
HAR	230	family 2N6758	n		200	5		64			? Harris	"1993"	BNL?	SSF Table
HAR	230	family 2N6798	n		200	5		70			7 Harris	"1993"	BNL?	SSF Table
HAR	230	family 2N6798	n		200	5		70			SEB/SEGR B WP-01	3/93	88in	W Will DC M9227 T= 45 deg C
		continued				5		80			SEB/SEGR B WP-01	1/93	88in	W Will DC M9227 T. 100 deg C
HAR	FRM240D1	2N7285	n	2.52	200	0		60/100(Fe)	80/100(Br)		SEGR J	91/92	BNL	100 deg C data has Vds(th)60/80(Br)
		continued		1 *		15		180/200(AT)			SEB J	91/92	88in	100 deg C data has no SEB "Not latest"
HAR	FRK250R	2N7293	n	4&3	200	0		140/160(Ni)	80/100(Br)		SEGR R WP.4	1 & 9/92	BNL	90 deg C Compare FRK230R
		continued		4&1		5		120/140(Ni)	80/100(Br)		SEGR			90 deg C
HAR	IRF9230		p		200	1				80/90(1)	? c	unknown	BNL	
HAR	FRM9240R	2N7318	p	583	200	0		Hard @ 200(Fe)	80/100(Br)		SEGR J	91/92	BNL	At 85 deg C, Vds(Fe)=120/180 @ Vgs=0
		continued				15		60/80(Ar)	100/120(Fe)	50(Br)	SEGR J	91/92	BNL/88in	Hard @200 for Ne
HAR	FRM9250		p	3	200	0		Hard @ 200(Ni)			N/A J	12/93	BNL	1 of 3 older version failed at Vds=200/Vgs= 0
		continued		3		15		Hard @ 200(Ni)			N/A J	12/93	BNL	Older version not tested at Vds=15
HAR	FRL234R		n	5	250	0		175/200(Ni)			SEGR R	3/93	BNL	90 deg C DC 9312
HAR	FRM234		n		250	5		238(Pass)			? Harris	"1993"	BNL?	SSF Table
HAR	FRK264D	2N7303			250	5		160			SEGR 9 WP-01	1 1/93	UW&88	Room temp & 100 deg C
HAR	FRM7360		n	2 & 4	400	0		225/250(Ni)	175/200(Br)		SEGR R	9/92	BNL	90 deg C
		continued		2 & 3		5		175/200(Ni)	200/225(Br)		SEGR			90 deg C
HAR		2N6800	n		400	5		130			SEB B WP-01	1/93	UW	DC8830 Temp= 28 deg C
		continued n				5		130			SEB B WPO,	1/93	UW	Temp . 100 deg C See preceding
HAR	420	family 2N6794	n		500	0		220			SEB B WPO1	-12/92	UW	Oberg Temp= 22 deg C
		continued				5		250			SEB B WP-01	"12/92	UW	Oberg Temp= 80 deg C
HAR	430	family 2N6802	n		500	0		250			SEB & SEGR B WP 01	"12/92	UW	Oberg 100 deg C
HAR	430	family 2N6762	n		500	5		280			? Harris	"1993	BNL?	SSF Table
HAR	IR450		p		500	0					SEB A	"9/93	88in	Koga

4: Power MOSFET Data

The Pass/Fail Vds Voltages for Indicated Beams of Columns H through L

Mfr	Mfr Number	Generic	Channel	Sample	BVds	Vgs(off)	Low Z fens	Fe, Ni, Co LET=27	Br or Kr LET=38	High Z Ions	High Energy ions	Failure Test	Org	Date	Location	Remarks
HAR	FRL430D		n		500	0		>400				SEB	HON WP-2	2/93	BNL	
	continued						Dynamic?		>400			SEB				
	continued								<400			Unk				
	continued								<250			Unk				
HAR	FRM450R		n	5&4	500	0		275/300 (Ni)	175/200 (Br)			SEGR	R	9/92&3/93	BNL	90 deg C Ni DC9232
	continued			5&1		5		200/225 (Ni)	100/125 (Br)			SEGR	R	9/92&3/93	BNL	90 deg C Ni DC9232
HAR	EN460		n		500	0			300 (Br)			SEGR	R	1992	BNL	Deleted from WP.04 design
HAR	TA6768		n	1	500	0	<320 (Cl)			<320 (I)		Gate leakage	C	1989	BNL	Early parts; ambiguous data LET(Cl)=12
HAR	TA9768		n		500	0	<320 (Cl)			<320 (I)		Gate leakage	C	1989	BNL	Early parts; ambiguous data LET(Cl) . 12
HAR	TA9783	IGBT	n	2	600	5		325/350 (Ni)				SEGR	R	12/92	BNL	room T